

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	13660	microfluid\$9	US- PGPUB; USPAT
2	BRS	L2	10136	1 and (wafer or substrate)	US- PGPUB; USPAT
3	BRS	L3	4845	2 and capillary	US- PGPUB; USPAT
4	BRS	L4	4078	1 and (transparent or glass) near8 (wafer or substrate)	US- PGPUB; USPAT
5	BRS	L5	2509	4 and capillary	US- PGPUB; USPAT
6	BRS	L6	2020	4 and pattern\$9 near8 (layer or substrate or cover or wafer or chip)	US- PGPUB; USPAT
7	BRS	L7	3192	1 and pattern\$9 near8 (layer or substrate or cover or wafer or chip)	US- PGPUB; USPAT
8	BRS	L8	227	7 and anodic near8 bond\$9	US- PGPUB; USPAT
9	BRS	L9	576	7 and dry near8 etch\$9	US- PGPUB; USPAT
10	BRS	L10	161	8 and silicon near8 (oxide or dioxide)	US- PGPUB; USPAT
11	BRS	L11	360	9 and silicon near8 (oxide or dioxide)	US- PGPUB; USPAT
12	BRS	L12	2020	7 and (transparent or glass) near8 (wafer or substrate)	US- PGPUB; USPAT
13	BRS	L13	182	8 and (transparent or glass) near8 (wafer or substrate)	US- PGPUB; USPAT
14	BRS	L14	419	9 and (transparent or glass) near8 (wafer or substrate)	US- PGPUB; USPAT